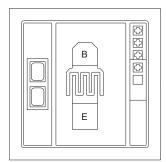


CP302-MPSH10

NPN - RF Transistor Die 50mA, 25 Volt

The CP302-MPSH10 is a silicon NPN RF transistor designed for low noise UHF/VHF amplifier and high output oscillator applications.



MECHANICAL SPECIFICATIONS:

14.5 x 14.5 MILS
9.0 MILS
2.3 x 2.3 MILS
2.5 x 2.3 MILS
AI – 30,000Å
Au – 18,000Å
4 INCHES
53,730

BACKSIDE COLLECTOR R

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Collector-Base Voltage	V_{CBO}	30	V
Collector-Emitter Voltage	V_{CEO}	25	V
Emitter-Base Voltage	V_{EBO}	3.0	V
Continuous Collector Current	IC	50	mA
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C

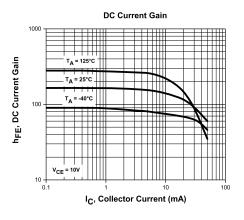
ELECTRICA	L CHARACTERISTICS: (TA=25°C unl	ess otherwise n	oted)	
SYMBOL I _{CBO}	TEST CONDITIONS V _{CB} =25V	MIN	MAX 100	UNITS nA
I _{EBO}	V _{EB} =2.0V		100	nA
BV_{CBO}	I _C =100μA	30		V
BV_{CEO}	I _C =1.0mA	25		V
BV EBO	I _E =10μA	3.0		V
V _{CE(SAT)}	I _C =4.0mA, I _B =0.4mA		0.50	V
V _{BE(ON)}	V _{CE} =10V, I _B =4.0mA		0.95	V
h _{FE}	V _{CE} =10V, I _C =4.0mA	60		
f_{T}	V_{CE} =10V, I_{C} =4.0mA, f=100MHz	650		MHz
C_{cb}	V_{CB} =10V, I_E =0, f=1.0MHz		0.70	pF
C_{rb}	V _{CB} =10V, I _E =0, f=1.0MHz	0.35	0.65	pF
rb'C _C	V _{CB} =10V, I _C =4.0mA, f=31.8MHz		9.0	ps

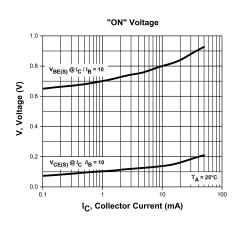
CP302-MPSH10

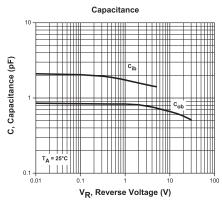
Typical Electrical Characteristics

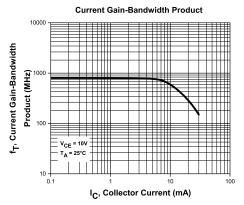


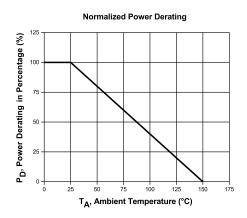
www.centralsemi.com





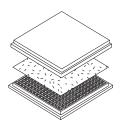






BARE DIE PACKING OPTIONS

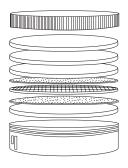




BARE DIE IN TRAY (WAFFLE) PACK

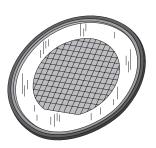
CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

R2 (3-April 2017)

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PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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